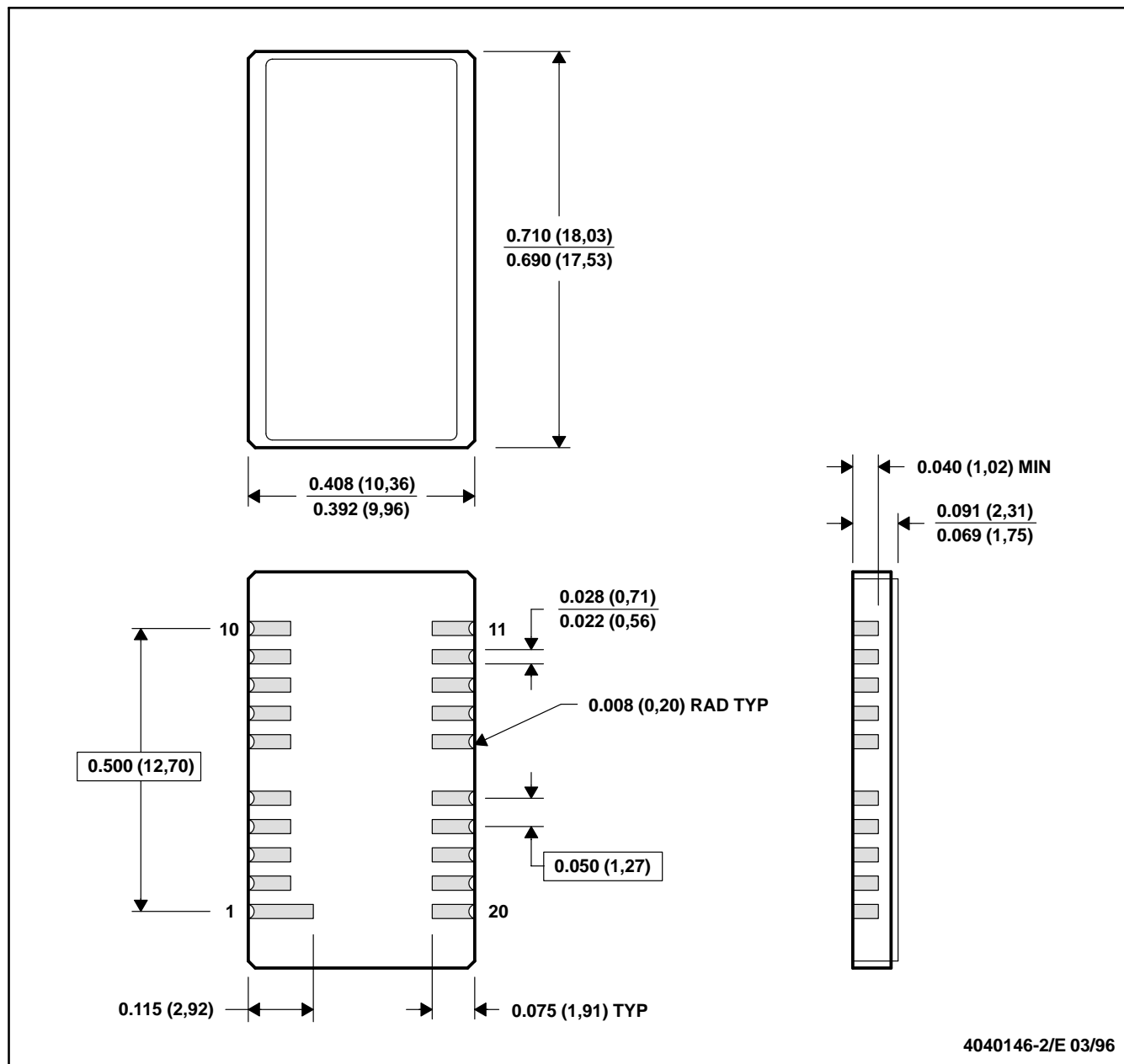


## HM (R-CDCC-N20)

## LEADLESS CERAMIC CHIP CARRIER



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a metal lid.  
 D. The terminals will be gold plated.

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